

US Patent & Trademark Office

Patent Public Search | Text View

United States Patent	12396314
Kind Code	B2
Date of Patent	August 19, 2025
Inventor(s)	Chang; Yi-Ming

Method of patterning a semiconductor layer

Abstract

A method of patterning semiconductor layer includes the following operations. A first electrode and a second electrode are formed within a substrate. A patterned polymer layer with a first portion on a portion of the second electrode and a second portion on an edge portion of the substrate is formed on the substrate. A semiconductor layer is deposited on the patterned polymer layer, the substrate, and the first electrode. The first portion of the patterned polymer layer and the semiconductor layer on the first portion are removed to form a through-hole in the semiconductor layer that exposes the portion of the second electrode. A conductive block is deposited on the semiconductor layer and in the through-hole.

Inventors:	Chang; Yi-Ming (Hsinchu, TW)
Applicant:	Raynergy Tek Incorporation (Hsinchu, TW)
Family ID:	1000008765858
Assignee:	Raynergy Tek Incorporation (Hsinchu, TW)
Appl. No.:	17/819792
Filed:	August 15, 2022

Prior Publication Data

Document Identifier	Publication Date
US 20230371293 A1	Nov. 16, 2023

Foreign Application Priority Data

TW	111117724	May. 11, 2022
----	-----------	---------------

Publication Classification

Int. Cl.: H10K30/81 (20230101); H10K71/00 (20230101)

U.S. Cl.:

CPC H10K30/81 (20230201); H10K71/621 (20230201);

Field of Classification Search

USPC: None

References Cited

U.S. PATENT DOCUMENTS

Patent No.	Issued Date	Patentee Name	U.S. Cl.	CPC
2010/0207112	12/2009	Fuerst et al.	N/A	N/A
2018/0261656	12/2017	Kim	N/A	H10K 71/221
2021/0249637	12/2020	Wang	N/A	H10K 50/11

FOREIGN PATENT DOCUMENTS

Patent No.	Application Date	Country	CPC
2554422	12/2017	GB	N/A
2009260134	12/2008	JP	N/A
2019506733	12/2018	JP	N/A
2020515326	12/2019	JP	N/A
2020031404	12/2019	WO	N/A

Primary Examiner: Whalen; Daniel

Attorney, Agent or Firm: Elmore Patent Law Group, P.C.

Background/Summary

CROSS-REFERENCE TO RELATED APPLICATION

(1) This application claims priority to Taiwan Application Serial Number 111117724, filed May 11, 2022, which is herein incorporated by reference in its entirety.

BACKGROUND

Field of Invention

(2) The present disclosure relates to a method of patterning a semiconductor layer.

Description of Related Art

(3) Devices with active matrix driving or reading signals have many applications, such as active-matrix organic light-emitting diodes (AMOLED) and photodiode-based image sensors. With the gradual miniaturization of photodiodes in the semiconductor industry, a good photodiode needs to remove the material at the connection between the electrode and the external wire to avoid the formation of high resistance between the electrode and the external wire, which affects the current generation. Moreover, the material around the photodiode also needs to be removed to form a good package and maintain the stability of the functional devices. Therefore, it is very important that the material is removed cleanly and removed in a proper position during the photodiode manufacturing process.

(4) In addition, the selection of photodiode materials has also developed from the previous silicon-based materials to organic semiconductor materials, quantum dot materials, or perovskite materials. The structure of the photodiodes has also changed to bottom-to-top layer stacking corresponding to the change of materials. The photoresist chemicals used in the fabrication process of this structure may be incompatible with emerging organic semiconductor materials, quantum dot materials, or perovskite materials. For example, the chemicals used in the lithography process may decompose organic semiconductor materials, quantum dots, and perovskite materials, making it difficult to pattern photodiodes based on perovskite materials, and it is difficult to obtain a good connection between the electrode and the external wire that does not cause high resistance or a good package that does not damage functional devices due to residual materials.

SUMMARY

(5) The present disclosure relates to a method of patterning a semiconductor layer. In some embodiments, the method includes the following operations. A first electrode and a second electrode are formed within a substrate. A patterned polymer layer is formed on the substrate, in which the patterned polymer layer has a first portion located on a portion of the second electrode and a second portion located on an edge portion of the substrate. A semiconductor layer is deposited on the patterned polymer layer, the substrate, and the first electrode. The first portion of the patterned polymer layer and the semiconductor layer located on the first portion are removed to form a through-hole in the semiconductor layer and expose the portion of the second electrode. A conductive block is deposited on the semiconductor layer and in the through-hole.

(6) In some embodiments, the method includes removing the second portion of the patterned polymer layer and the semiconductor layer located on the second portion to expose the edge portion of the substrate while removing the first portion of the patterned polymer layer and the semiconductor layer located on the first portion.

(7) In some embodiments, the method includes removing the second portion of the patterned polymer layer and the semiconductor layer located on the second portion to expose the edge portion of the substrate after depositing the conductive block on the semiconductor layer and the through-hole.

(8) In some embodiments, the semiconductor layer includes a photoactive layer, a carrier transport layer, or a combination thereof. The material of the photoactive layer includes organic semiconductors, quantum dots, perovskites, or combinations thereof.

(9) In some embodiments, the patterned polymer layer includes an epoxy resin, a polyimide, an acrylic, or combinations thereof.

(10) In some embodiments, the second portion of the patterned polymer layer has a continuous shape located on the edge portion of the substrate in the top view.

(11) In some embodiments, the conductive block in the through-hole completely fills the through-hole.

(12) In some embodiments, the first portion of the patterned polymer layer is removed by mechanically tearing off.

(13) In some embodiments, the method further includes forming a package layer on the edge portion of the substrate after depositing the conductive block on the semiconductor layer and in the through-hole.

(14) In some embodiments, the method includes forming a release layer on the substrate before forming a patterned polymer layer on the substrate and removing the release layer under the first portion while removing the first portion of the patterned polymer layer and the semiconductor layer located on the first portion.

(15) In some embodiments, the method includes removing the second portion of the patterned polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate.

(16) In some embodiments, the method includes removing the second portion of the patterned

polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate while removing the release layer under the first portion.

(17) In some embodiments, the method includes removing the second portion of the patterned polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate after depositing the conductive block on the semiconductor layer and in the through-hole.

(18) In some embodiments, the release layer includes water-soluble polymers, fluorine-containing organic molecules, or combinations thereof.

(19) In some embodiments, the water-soluble polymer has a hydroxyl group, an ether group, an amine group, or a sulfonic acid group.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

(1) When reading the accompanying drawings of the present disclosure, an understanding of various aspects of the present disclosure is suggested from the following description. It is noted that, according to standard industry practice, the various feature dimensions are not drawn to scale. Various feature sizes may be arbitrarily increased or decreased to clarify the discussion.

(2) FIG. 1 is a cross-sectional view of a photodiode structure formed according to some embodiments of the present disclosure.

(3) FIG. 2 is a flowchart of a method of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure.

(4) FIG. 3 is a flow diagram of a method of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure including a release layer.

(5) FIGS. 4-6 are cross-sectional views of intermediate stages of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure.

(6) FIG. 7 is a top view of an intermediate stage of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure.

(7) FIGS. 8A-8B are intermediate stage cross-sectional views of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure.

(8) FIGS. 9A-9C are intermediate stage cross-sectional views of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure.

(9) FIGS. 10-12 are intermediate stage cross-sectional views of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure including a release layer.

(10) FIG. 13 is an intermediate stage top view of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure including a release layer.

(11) FIGS. 14A-14B are intermediate stage cross-sectional views of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure including a release layer.

(12) FIGS. 15A-15C are intermediate stage cross-sectional views of patterning a semiconductor layer to form a photodiode structure according to some embodiments of the present disclosure including a release layer.

DETAILED DESCRIPTION

(13) Different embodiments are provided below to illustrate different features of the present disclosure. To simplify the present disclosure, specific examples of elements and configurations are presented below. Of course, these are only examples and are not intended to be limiting. For

example, the description below that the first feature is formed above the second feature may include an embodiment in which the first feature and the second feature are formed in direct contact, and may also include embodiments in which other features formed between the first feature and the second feature so that the first feature and the second feature are not formed in direct contact.

(14) Furthermore, spatially relative terms, such as below and above, etc., may be used herein to describe the relationship of one element or feature to another element or feature in the figures. In addition to the orientation depicted in the figures, spatially relative terms are intended to encompass different orientations of the device in use or operation. The device may be otherwise oriented (rotated 90 degrees or otherwise) and the description herein using spatial relative may likewise be interpreted accordingly. In the discussion herein, unless otherwise indicated, the same reference numbers in different figures refer to the same or similar elements formed by the same or similar methods using the same or similar materials.

(15) The present disclosure provides a method of patterning a semiconductor layer, the method includes the following operations: A first electrode and a second electrode are formed within a substrate. A patterned polymer layer is formed on the substrate, in which the patterned polymer layer has a first portion on a portion of the second electrode and a second portion on an edge portion of the substrate. A semiconductor layer is deposited on the patterned polymer layer, the substrate, and the first electrode. The first portion of the patterned polymer layer and the semiconductor layer on the first portion are removed to form a through-hole in the semiconductor layer and expose the portion of the second electrode. A conductive block is deposited on the semiconductor layer and in the through-hole. Hereinafter, the method of patterning a semiconductor layer of the present disclosure will be described in detail according to embodiments.

(16) FIG. 1 is a cross-sectional view of a photodiode structure formed according to some embodiments of the present disclosure. FIG. 2 and FIG. 3 are flowcharts of methods of patterning semiconductor layers to form photodiode structures according to some embodiments of the present disclosure. The difference between FIG. 2 and FIG. 3 is that the method in FIG. 3 further includes forming and removing a release layer. The photodiode structure in FIG. 1 includes a substrate **101**, a first electrode **103**, a second electrode **105**, a semiconductor layer **107**, a conductive block **109**, a package layer **111**, and a through-hole **H1**, in which the semiconductor layer **107** may include materials, such as organic semiconductors, quantum dots, perovskites, or combinations thereof, which are incompatible with the chemicals used in current lithography process and need to be formed by a solution-type process. That is, semiconductor layer **107** shown in FIG. 1 has the characteristics of being difficult to be patterned. However, the purpose of patterning the semiconductor layer **107** can be achieved by the methods shown in FIG. 2 and FIG. 3, in which the semiconductor layer **107** is formed on a patterned polymer layer (e.g., the patterned polymer layer **113** discussed below). The position where the patterned polymer layer **113** is formed corresponds to the position where the semiconductor layer **107** is about to be patterned. For example, the portion **105A** of the second electrode **105** corresponds to the position of the through-hole **H1** in the semiconductor layer **107**. Thus, when the semiconductor layer **107** is formed on substrate **101** with the patterned polymer layer **113** thereon, the semiconductor layer **107** with a patterned polymer layer thereunder can be removed simultaneously by removing the patterned polymer layer, and the semiconductor layer **107** with no patterned polymer layer thereunder remains on the substrate **101** to achieve the purpose of patterning the semiconductor layer.

(17) Next, the photodiode structure of FIG. 1 formed by a method **200** of patterning the semiconductor layer of FIG. 2 will be described in detail. In operation **202** of FIG. 2, the first electrode **103** and the second electrode **105** are formed within substrate **101** with reference to the intermediate stage cross-sectional view of forming the photodiode structure in FIG. 4. In some embodiments, the substrate **101** is a transparent substrate, such as a flexible polyethylene terephthalate (PET), a polyethylene naphthalate (PEN), a polyimide (PI) or, for example, a non-

flexible glass substrate, and a silicon wafer-like substrate. In some embodiments, substrate **101** is a thin film transistor (TFT) substrate. In some embodiments, substrate **101** is a complementary metal oxide semiconductor (CMOS) substrate. In some embodiments, substrate **101** contains circuitry. In the embodiment shown in FIGS. **1** and **4**, the first electrode **103** and the second electrode **105** are spatially separated from each other. In some embodiments, the first electrode **103** is a unit electrode. There may be a plurality of them as shown in FIG. **1** and FIG. **4**, and they are separated from each other and arranged such as in arrays corresponding to the position of the pixel (not shown) in the semiconductor layer **107** to be formed thereon in subsequent processes. In some embodiments, the second electrode **105** is a connected electrode as shown in FIG. **1**, connecting the conductive block **109** to be formed thereon in the subsequent process and connecting the driving or readout circuit (not shown) in the substrate **101** to form an electrical circuit. It should be noted that, for illustration, the substrate **101** of the present disclosure is a substrate of an element unit, and the drawings provided in the present disclosure only schematically depict a single element unit. However, those skilled in the art should know that, in the actual process, there may be multiple element units so that the substrate is a common substrate of multiple element units. And the operations to be discussed below are performed on the common substrate. The operation, such as forming a patterned polymer layer on a common substrate, allows each element unit to form a photodiode structure as in the drawings provided in present disclosure, including the through-hole and package layer discussed below.

(18) Next, in operation **204** of FIG. **2**, also referring to the intermediate stage cross-sectional view of forming the photodiode structure in FIG. **5**. The patterned polymer layer **113** is formed on the substrate **101**, where the patterned polymer layer **113** has a first portion **113A** on the portion **105A** of the second electrode **105**, and a second portion **113B** on the edge portion **101B** of the substrate **101**, which define the position of the pattern where the semiconductor layer **107** to be formed thereon in a subsequent process. That is to say, the first portion **113A** defines the position of the through-hole H1 in the semiconductor layer **107** in the photodiode structure in FIG. **1** so that the conductive block **109** can fill the through-hole H1 and then connect to the second electrode **105** to form an electrical circuit. The second portion **113B** defines the position of the recess H2 in the semiconductor layer **107** in the photodiode structure in FIG. **1** so that the package layer **111** can cover the recess H2 and protect the photodiode structure from the infiltration of external oxygen or moisture, which may affect normal functioning. In some embodiments, the patterned polymer layer **113** may include epoxy resin, polyimide, acrylic, or combinations thereof, in which the polyimide is, for example, general polyimide or photosensitive polyimide amine. In some embodiments, the patterned polymer layer **113** may also include other materials that can be cured or cross-linked through heat, light, or chemical means. It should be noted that the patterned polymer layer **113** has mechanical toughness so that it will not be broken or broken when removed in subsequent processes, and can also be patterned by a lithography process or a necessary etching process. In some embodiments, the patterned polymer layer **113** is directly formed with the first portion **113A** and the second portion **113B** on the substrate **101** by printing, such as screen printing, inkjet, or stencil printing. In some embodiments, the patterned polymer layer **113** is formed by exposing and developing the polymer layer (not shown) on substrate **101** to form the first portion **113A** and the second portion **113B**. In some embodiments, the patterned polymer layer **113** is formed by laminating the dry film photoresist layer on the polymer layer (not shown) on the substrate **101**, and then etching the polymer layer after defining the first portion **113A** and the second portion **113B** by exposing and developing the dry film photoresist layer to obtain a patterned polymer layer **113** having a first portion **113A** and a second portion **113B**, and finally, the dry film photoresist layer is removed. In some embodiments, the patterned polymer layer **113** is formed by spin coating a photoresist layer (not shown) on the polymer layer (not shown) on the substrate **101**, and then etching the polymer layer after defining the first portion **113A** and the second portion **113B** by exposing and developing the dry film photoresist layer to obtain the patterned polymer layer **113**.

having the first portion **113A** and the second portion **113B**, and finally, the dry film photoresist layer is removed.

(19) Next, in operation **206** of FIG. 2, referring to FIG. 6 and FIG. 7, the intermediate stage cross-sectional view and the top view of forming the photodiode structure, the semiconductor layer **107** is deposited on the patterned polymer layer **113**, the substrate **101** and the first electrode **103**. The semiconductor layer **107** includes a photoactive layer and necessary multiple layers of carrier transport layers (not shown), and the materials of the photoactive layer may include organic semiconductors, quantum dots, perovskites, or combinations thereof, such as a perovskite mineral quantum dot having the general formula ABX_3 , in which A can be formamidinium (FA), methylammonium (MA), cesium or combinations thereof; B can be lead, tin or a combination thereof; and X can be a halogen, or, for example, an organic semiconductor layer, such as P3HT:PCBM, PTB7:PCBM, PM6:Y6, conjugated polymer: fullerene derivative, conjugated polymer: non-fullerene acceptor, conjugated polymer: conjugated polymer, conjugated small molecule: conjugated small molecule, conjugated small molecule: conjugated Polymer, etc., but not limited to this, or cadmium selenide (CdSe), cadmium sulfide (CdS), zinc sulfide (ZnS), indium phosphide (InP), lead sulfide (PbS) and other quantum dot materials, but not limited thereto, or an organic semiconductor in a light emitting type, such as poly[2-methoxy-5-(2-ethylhexyloxy)-1,4-phenylenevinylene](MEH-PPV), but not limited thereto. The materials of the photoactive layer have excellent photoelectric conversion efficiency; however, due to their own characteristics, these materials are often formed by a solution-type process such as spin coating. In some embodiments, the semiconductor layer **107** is not limited to a single layer, for example, it may have a stack structure of multiple layers, and each has a carrier transport layer above and below the photoactive layer to help collect electrons and holes to the first electrode **103** and the conductive block **109** on semiconductor layer **107** to be discussed below. In the top view of FIG. 7, a line A-A marks the cross-sectional position of FIG. 6, and the dotted line marks the perspective location of the first portion **113A** and the second portion **113B** of the patterned polymer layer **113** covered by the semiconductor layer **107**. It should be noted that the second portion **113B** of the patterned polymer layer **113** has a continuous shape on the edge portion **101B** of the substrate **101** in a top view shown in FIG. 7, in which a continuously wrapping rectangular strip is located at the edge of the photodiode structure and surround the internal elements, such as the first electrode **103** under the semiconductor layer **107**, etc.

(20) Next, in operation **208A** of FIG. 2, also referring to FIG. 8A, the intermediate stage cross-sectional view of the photodiode structure, the second portion **113B** of patterned polymer layer **113** and the semiconductor layer **107** thereon are removed while removing the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon to form a recess H2 in the semiconductor layer **107** and expose the edge portion **101B** of the substrate **101**. In FIG. 7, it is known that the second portion **113B** of the patterned polymer layer **113** has a continuous shape on the edge portion **101B** of the substrate **101** in a top view, therefore, removing the left and right parts of the second portion **113B** as shown in FIG. 6 to obtain the recess H2 as shown in FIG. 8A is substantially removing them as one body. In some embodiments, the patterned polymer layer **113** is torn off mechanically. Since the patterned polymer layer **113** has mechanical toughness, it will not be broken or broken during tearing off. A patterned semiconductor layer **107** is obtained by operation **208A** and has patterns of the through-hole H1 the recess H2 substantially free of residual semiconductor layer **107** thereon. The method for patterning a semiconductor layer provided by the present disclosure can not only pattern the semiconductor layer **107** that is incompatible with the lithography process due to its own characteristics (such as being miscible with the solvent used in the lithography process or causing chemical reactions, etc.) but also can be used to pattern the semiconductor layer **107** according to the desired pattern after the photodiode structure is miniaturized.

(21) Next, in operation **210A** of FIG. 2, also referring to FIG. 8B, the intermediate stage cross-

sectional view of forming the photodiode structure, a conductive block **109** is deposited on the semiconductor layer **107** and in the through-hole **H1**. The conductive block **109** in the through-hole **H1** completely fills the through-hole **H1** and is well connected to the portion **105A** of the second electrode **105**, thus the resistance is not too high due to the presence of the semiconductor layer **107** in the through-hole **H1**, which may affect current generation. The conductive block **109** on the semiconductor layer **107** is spatially separated from the first electrode **103** by the semiconductor layer **107** to avoid short circuits caused by direct contact with the first electrode **103**. In some embodiments, the conductive block **109** on the semiconductor layer **107** is a common electrode of the pixels in the semiconductor layer **107** compared to the unit electrodes arranged corresponding to the pixel positions in the semiconductor layer **107** such as the first electrode **103** shown in FIG. 1. In some embodiments, the materials of the conductive block **109** may be metal, such as aluminum, silver, molybdenum, copper, titanium, titanium nitride (TiN), etc.; metal oxides, such as indium tin oxide (ITO), etc.; carbon-based materials, such as carbon nanotubes, etc.; and organic conductive materials, etc. In some embodiments, the first electrode **103** acts as an anode, and the conductive block **109** on the semiconductor layer **107** acts as a cathode, or the first electrode **103** acts as a cathode and the conductive block **109** on the semiconductor layer **107** acts as an anode. In some embodiments, the anode and the cathode are connected to a voltage source (not shown) to collect the current generated by the semiconductor layer **107**. In some embodiments, the transistor circuits and capacitors are disposed in the substrate **101**. In some embodiments, the method of depositing the conductive block **109** includes the following operations: before depositing the conductive block **109**, forming a mask (not shown) on the substrate **101** having the semiconductor layer **107** thereon, thus the mask covers the edge portion **101B** of the substrate **101** and exposes the semiconductor layer **107** and the through-hole **H1** therein, then depositing the conductive block **109** on the exposed parts from the mask, and then removing the mask to obtain the photodiode structure shown in the cross-sectional view of FIG. 8B, in which the edge portion **101B** of the substrate **101** covered by the mask retains the pattern of the recess **H2** of the semiconductor layer **107**, and the package layer **111** can be formed thereon in the subsequent process.

(22) Next, in operation **212A** of FIG. 2, a package layer **111** is formed on the edge portion **101B** of the substrate **101** as shown in FIG. 8B to obtain the photodiode structure as shown in FIG. 1. In some embodiments, the materials of the package layer **111** include silicon nitride, silicon oxynitride, silicon oxide, epoxy resin, etc., or combinations thereof.

(23) Next, returning to operation **206** of FIG. 2, in addition to continuing operation **208A** to simultaneously remove the first portion **113A** and the second portion **113B** of the patterned polymer layer **113**, operation **208B** can be performed, and only the first portion **113A** of the patterned polymer layer **113** is removed. In operation **208B**, while referring to FIG. 9A, the intermediate stage cross-sectional view of forming the photodiode structure, the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed to form the through-hole **H1** in the semiconductor layer **107** and expose the portion **105A** of the second electrode **105**. Next, in operation **210B**, while referring to FIG. 9B, the intermediate stage cross-sectional view of forming the photodiode structure, and a conductive block **109** is deposited on the semiconductor layer **107** and in the through-hole **H1**. Since the second portion **113B** of the patterned polymer layer **113** is still on the edge portion **101B** of the substrate **101**, the second portion **113B** can be used to define the location where to deposit the conductive block **109**, thereby reducing the cost of additional process operation for patterning the conductive block **109**, such as forming an additional mask to pattern the conductive block **109** in the above-mentioned operation **210A** and making the material selection of the conductive block **109** more diverse for the materials of the conductive block **109** that are difficult to be patterned. Next, in operation **212B**, while referring to FIG. 9C, the intermediate-stage cross-sectional view of forming the photodiode structure, the second portion **113B** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed after depositing the conductive block **109** on the semiconductor layer **107**

and in the through-hole H1. The recess H2 is formed in the semiconductor layer **107** to expose the edge portion **101B** of the substrate **101**. Different from operations **208A-210A**, operations **208B-212B** can selectively remove the patterned polymer layer **113** at different positions in different process stages, that is, the first portion **113A** and the second portion **113B**. Therefore, the patterning of the semiconductor layer **107** can also be selectively achieved, and the process method is more diverse. In addition, operation **208B** and operation **212B** are basically the same as operation **208A**; operation **210B** is basically the same as operation **210A**, and details are not repeated here. In conclusion, operations **208B-212B** are the same as operations **208A-210A**, to obtain the patterns of the through-hole H1 and the recess H2 in the semiconductor layer **107**, and the method provided by the present disclosure can still be used to pattern the semiconductor layer **107** according to the desired pattern after the miniaturization of the photodiode structure. After operations **208B-212B**, operation **214B** is performed to form a package layer **111** on the edge portion **101B** of the substrate **101** as shown in FIG. 9C to obtain the photodiode structure as shown in FIG. 1. Operation **214B** is basically the same as operation **212A**, and details are not repeated here.

(24) Next, the photodiode structure of FIG. 1 formed by a method **300** of patterning the semiconductor layer of FIG. 3 will be described in details. Different from FIG. 2, the method **300** of FIG. 3 further includes forming and removing a release layer. The release layer may include materials with low surface energy and/or low adhesion. In some embodiments, the release layer may include a water-soluble polymer, a fluorine-containing organic molecule, or a combination thereof. Specifically, the water-soluble polymers refer to polymer materials with cationic groups, anionic groups, or polar nonionic groups, such as hydroxyl groups, ether groups, sulfonic acid groups, and/or amine groups. In some embodiments, the water-soluble polymers may include polyvinyl alcohol, polystyrene sulfonic acid, polyacrylamide, or combinations thereof, but is not limited thereto. In some embodiments, the fluorine-containing organic molecules may include fluorine-based polymers, such as poly(1,1,2,2-tetrafluoroethylene) (PTFE), poly(1,1-difluoroethylene) (PVDF), derivatives of the above molecules, or combinations thereof. It should be noted that the purpose of the release layer is to reduce the adhesion of the patterned polymer layer on the substrate and to facilitate the removal of the patterned polymer layer from the substrate in the subsequent process. In detail, in method **200** of FIG. 2, the patterned polymer layer **113** is formed in direct contact with substrate **101** and has high adhesion. To make the patterned polymer layer **113** easier to be removed from substrate **101**, an easily detached release layer is formed between the substrate **101** and the patterned polymer layer **113**. In operation **302** of FIG. 3, also referring to FIG. 10, the intermediate stage cross-sectional view of forming the photodiode structure, the first electrode **103** and the second electrode **105** are formed within the substrate **101**, and then the release layer **115** is formed thereon before forming the patterned polymer layer. Except for forming the release layer **115**, operation **302** is basically the same as operation **202**, and details are not repeated here.

(25) Next, in operation **304** of FIG. 3, also referring to the intermediate stage cross-sectional view of forming the photodiode structure in FIG. 11, the patterned polymer layer **113** is formed on the substrate **101**, more precisely, on the release layer **115** above the substrate **101**. Except for the release layer **115**, operation **304** is basically the same as operation **204**, and details are not repeated here. In addition, since the release layer **115** is easier detached from the substrate **101** than the patterned polymer layer **113**, when the polymer layer (not shown) is patterned by the same method as operation **204**, the patterned release layer **115** (not shown) can be simultaneously obtained as shown in FIG. 11. For example, in the embodiment in which the patterned polymer layer **113** is formed by exposing and developing the polymer layer (not shown) on the substrate **101** to form the first portion **113A** and the second portion **113B**, because the release layer **115** is more easily detached from the substrate **101**, when the polymer layer is developed to form the patterned polymer layer **113**, the release layer **115** under the uncured polymer layer is also developed and removed. That is to say, in addition to forming the patterned polymer layer **113** as in operation **204**,

operation **304** also forms the patterned release layer **115**. Same as the patterned polymer layer **113**, the patterned release layer **115** has the first portion **115A** on the portion **105A** of the second electrode **105**, and the second portion **115B** on the edge portion **101B** of the substrate **101** as shown in FIG. **11**.

(26) Next, in operation **306** of FIG. **3**, also referring to FIG. **12** and FIG. **13**, the intermediate stage cross-sectional view and top view of forming the photodiode structure, the semiconductor layer **107** is deposited on the patterned polymer layer **113**, the substrate **101**, and the first electrode **103**. Except for the release layer **115**, operation **306** is basically the same as operation **206**, and details are not repeated here.

(27) Next, in operation **308A** of FIG. **3**, also referring to FIG. **14A**, the intermediate stage cross-sectional view of forming the photodiode structure, the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed to form the through-hole **H1** in the semiconductor layer **107** and expose the portion **105A** of the second electrode **105**. Compared with operation **208A**, operation **308A** further includes the release layer **115**. Since the release layer **115** is more easily detached from the substrate **101** when the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed, the release layer **115** thereunder is removed simultaneously, that is, the first portion **115A** of the release layer **115** is removed. Same as operation **208A**, operation **308A** further includes simultaneously removing the second portion **113B** of the patterned polymer layer **113** and the semiconductor layer **107** thereon when removing the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon to form the recess **H2** in the semiconductor layer **107** and expose the edge portion **101B** of the substrate **101**. Similarly, when the second portion **113B** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed, the release layer **115** thereunder is removed simultaneously, that is, the second portion **115B** of the release layer **115** is removed. Except for the release layer **115**, operation **308A** is basically the same as operation **208A**, and details are not repeated here. All in all, operation **308A** is the same as operation **208A** to obtain the patterns of the through-hole **H1** and the recess **H2** in the semiconductor layer **107**, and the method provided by the present disclosure can still pattern the semiconductor layer **107** according to the desired pattern after the photodiode structure is miniaturized.

(28) Next, in operation **310A** of FIG. **3**, also referring to FIG. **14B**, the intermediate stage cross-sectional view of forming the photodiode structure, a conductive block **109** is deposited on the semiconductor layer **107** and in the through-hole **H1**. The conductive block **109** in the through-hole **H1** completely fills the through-hole **H1** and is well connected to the portion **105A** of the second electrode **105**. Since there is no semiconductor layer **107** in the through-hole **H1**, the resistance will not be too high to affect the current generation. The conductive block **109** on the semiconductor layer **107** is spatially separated from the first electrode **103** by the semiconductor layer **107** to avoid short circuits caused by direct contact with the first electrode **103**. Operation **310A** is basically the same as operation **210A**, and details are not repeated here.

(29) Next, in operation **312A** of FIG. **3**, a package layer **111** is formed on the edge portion **101B** of the substrate **101** (as shown in FIG. **14B**) to obtain the photodiode structure (as shown in FIG. **1**). Operation **312A** is basically the same as operation **212A**, and details are not repeated here.

(30) Next, returning to operation **306** of FIG. **3**, in addition to continuing operation **308A** to simultaneously remove the first portion **113A** and the second portion **113B** of the patterned polymer layer **113**, operation **308B** can be performed in which only the first portion **113A** of the patterned polymer layer **113** is removed. In operation **308B**, also referring to FIG. **15A**, the intermediate stage cross-sectional view of forming the photodiode structure, the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed to form the through-hole **H1** in the semiconductor layer **107** and expose the portion **105A** of the second electrode **105**. Since operation **308B** further includes the release layer **115**, when the first portion **113A** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed, the

release layer **115** thereunder will be removed simultaneously, that is, the first portion **115A** of the release layer **115** is removed. Next, in operation **310B**, also referring to FIG. **15B**, the intermediate stage cross-sectional view of forming the photodiode structure, a conductive block **109** is deposited on the semiconductor layer **107** and in the through-hole **H1**. Except for the release layer **115**, operation **310B** is basically the same as operation **210B**, and details are not repeated here. Next, in operation **312B**, also referring to FIG. **15C**, the intermediate stage cross-sectional view of forming the photodiode structure, after depositing the conductive block **109** on the semiconductor layer **107** and in the through-hole **H1**, the second portion **113B** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed to form a recess **H2** in the semiconductor layer **107** and expose the edge portion **101B** of the substrate **101**. Similarly, when the second portion **113B** of the patterned polymer layer **113** and the semiconductor layer **107** thereon are removed, the release layer **115** thereunder is removed simultaneously, that is, the second portion **115B** of the release layer **115** is removed. Different from operations **308A-310A**, operations **308B-312B** can selectively remove the patterned polymer layer **113** at different positions in different process stages, such as the first portion **113A** and the second portion **113B**, so the patterning of the semiconductor layer **107** can be selectively achieved as well and the process method is more diverse. In addition, operation **308B** and operation **312B** are basically the same as operation **308A**; operation **310B** is basically the same as operation **310A**, and details are not repeated here. To conclude, operations **308B-312B** are the same as operations **308A-310A**, to obtain the patterns of the through-hole **H1** and the recess **H2** in the semiconductor layer **107**, and the method provided by the present disclosure can still pattern the semiconductor layer **107** according to the desired pattern after the photodiode structure is miniaturized. After operations **308B-312B**, operation **314B** is performed to form the package layer **111** on the edge portion **101B** of the substrate **101** (as shown in FIG. **15C**) to obtain the photodiode structure (as shown in FIG. **1**). Operation **314B** is basically the same as operation **312A**, details are not repeated here.

(31) The present disclosure provides a method of patterning a semiconductor layer. The semiconductor layer **107**, which can only be coated on a photodiode structure by a solution-type process, is formed on a patterned polymer layer **113**. When the semiconductor layer **107** is formed on the substrate **101** having the patterned polymer layer **113** thereon, the semiconductor layer **107** can be removed simultaneously by removing the patterned polymer layer **113** thereunder. The semiconductor layer **107** having no patterned polymer layer **113** thereunder remains. The desired pattern such as the through-hole **H1** and the recess **H2** in the semiconductor layer **107** can be obtained, thereby achieving the purpose of patterning the semiconductor layer **107** and solving the problem that the semiconductor layer **107** is difficult to be compatible with the chemicals used in the lithography process due to its own characteristics.

(32) The foregoing outlines the features of some embodiments to enable those of ordinary skill in the art to better understand the aspects of the present disclosure. Those of ordinary skill in the art should realize that they may at any time utilize the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments presented herein. Those of ordinary skill in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure and that they can make various changes, substitutions, and modifications herein without departing from the spirit and scope of the present disclosure.

Claims

1. A method of patterning a semiconductor layer, comprising: forming a first electrode and a second electrode within a substrate; forming a patterned polymer layer on the substrate, wherein the patterned polymer layer has a first portion located on a portion of the second electrode and a second portion located on an edge portion of the substrate; depositing the semiconductor layer on

the patterned polymer layer, the substrate, and the first electrode; removing the first portion of the patterned polymer layer and the semiconductor layer located on the first portion to form a through-hole in the semiconductor layer to expose the portion of the second electrode; and depositing a conductive block on the semiconductor layer and in the through-hole, wherein the conductive block in the through-hole completely fills the through-hole.

2. The method of claim 1, further comprising: removing the second portion of the patterned polymer layer and the semiconductor layer located on the second portion to expose the edge portion of the substrate while removing the first portion of the patterned polymer layer and the semiconductor layer located on the first portion.

3. The method of claim 1, further comprising: after depositing the conductive block on the semiconductor layer and the through-hole, removing the second portion of the patterned polymer layer and the semiconductor layer located on the second portion to expose the edge portion of the substrate.

4. The method of claim 1, wherein the semiconductor layer comprises a photoactive layer, a carrier transport layer, or a combination thereof, and a material of the photoactive layer comprises an organic semiconductor, a quantum dot, a perovskite, or combinations thereof.

5. The method of claim 1, wherein the patterned polymer layer comprises an epoxy resin, a polyimide, an acrylic, or combinations thereof.

6. The method of claim 1, wherein the second portion of the patterned polymer layer has a continuous shape located on the edge portion of the substrate from a top view.

7. The method of claim 1, wherein the first portion of the patterned polymer layer is removed by mechanically tearing off.

8. The method of claim 1, further comprising: after depositing the conductive block on the semiconductor layer and in the through-hole, forming a package layer on the edge portion of the substrate.

9. The method of claim 1, further comprising: forming a release layer on the substrate before forming the patterned polymer layer on the substrate; and removing the release layer under the first portion while removing the first portion of the patterned polymer layer and the semiconductor layer located on the first portion.

10. The method of claim 9, further comprising: removing the second portion of the patterned polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate.

11. The method of claim 9, further comprising: removing the second portion of the patterned polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate while removing the release layer under the first portion.

12. The method of claim 9, further comprising: after depositing the conductive block on the semiconductor layer and in the through-hole, removing the second portion of the patterned polymer layer, the semiconductor layer on the second portion, and the release layer under the second portion to expose the edge portion of the substrate.

13. The method of claim 9, wherein the release layer comprises a water-soluble polymer, a fluorine-containing organic molecule, or a combination thereof.

14. The method of claim 13, wherein the water-soluble polymer has a hydroxyl group, an ether group, an amine group, or a sulfonic acid group.
